

Product Features

- Supports clock requirements for Mobile Pentium[®] Processor
- 2 Host and 5 PCI clocks
- Separate supply pins for mixed (3.3/2.5V) voltage application.
- <175ps skew among CPU clocks.</p>
- < 250ps skew among PCI clocks.</p>
- 48mhz for USB.

Block Diagram

- 28-pin SSOP package for minimum board space.
- Power management capabilities

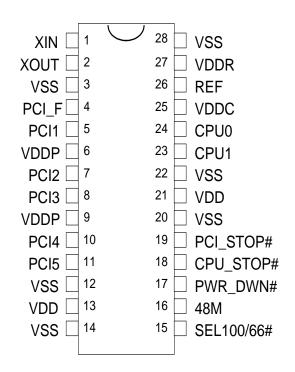
Frequency Table

SEL100/66#	CPU	PCI
0	66.4 Mhz*	33.3 Mhz
1	99.8 Mhz**	33.2 MHz
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*Down Spread 1.25% (total); **Down Spread .5% (total)

VDDR XIN REF OSC XOUT VDDC CPUCLK (0:1) CPU_STOP# PLL PCI_STOP# VDDP SEL1066# PCI (1:5) PWR DWN# PCI_F 48 MHz PLL

Pin Configuration





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Mobile Pentium® Processor Application Clock Generator with SSCG, USB and Power Management Support

PIN No.	Pin Name	PWR	I/O	TYPE	PE Description					
1		VDD		OSC1	On-chip reference oscillator input pin. Requires either an					
I	XIN	VDD	I	0301						
					external parallel resonant crystal (nominally 14.318 MHz) or					
0	XOUT		_	0004	externally generated reference signal					
2	XOUT	VDD	0	OSC1	On-chip reference oscillator output pin. Drives an external					
					parallel resonant crystal. When an externally generated					
					reference signal is used at Xin, this pin is left unconnected					
15	SEL100/66#	-	I	PADI4	Frequency select input pins. See frequency select table on					
					page 1.					
23, 24	CPUCLK	VDDC	0	BUF1	Clock outputs. CPU frequency table specified on page 1.					
	(0:1)									
4	PCI_F	VDDP	0	BUF4	Free running PCI clock. When PCI_STP# = 0, this clock does					
					NOT stop.					
16	48M	VDD48	0	BUF3	48 MHz fixed clock.					
5, 7, 8,	PCI(1:5)	VDDP	0	BUF4	PCI bus clocks. See frequency select table on page 1.					
10, 11										
26	REF	VDDR	0	BUF3	Buffered outputs of on-chip reference oscillator.					
19	PCI STOP#	-		PAD	When driven to a logic low level, this pin will synchronously stop					
	—			PU	all PCI clocks (except PCI_F) at a logic low level.					
18	CPU_STOP#	-		PAD	When driven to a logic low level, this pin will synchronously stop					
				PU	all CPU clocks at a logic low level.					
17	PWR DWN#	-	I	PAD	This pin is active low. When asserted low, the device is in					
				PU	shutdown mode. VCO's, Crystal, and outputs are turned off.					
13, 21	VDD	-	Р	-	3.3 volt power supply for core logic.					
3, 12,	VSS	-	Р	-	Ground pins for the device.					
14, 20,			•							
22, 28										
9,6	VDDP	-	Р	-	3.3 Volt power supply pins for PCI (1:5) and PCI_F clock ou					
-, -			-		buffers.					
25	VDDC	-	Р	-	3.3 or 2.5 Volt power supply for CPUCLK (0:1) outputs.					
27	VDDR	-	Р		3.3 Volt power supply pins for reference clock output buffers					
					and crystal circuit.					

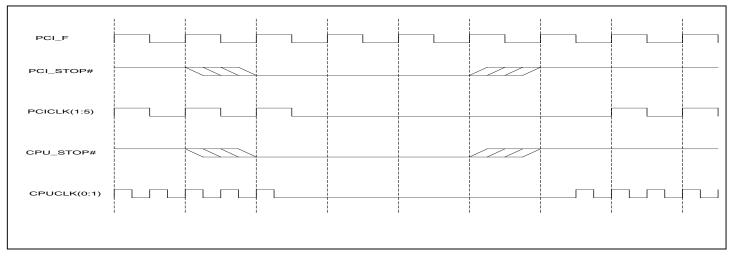


Power Management Functions

All PCI (excluding PCI_F) and CPU clocks can be enabled or stopped via the PCI_STOP# and CPU_STOP# input pins. All clocks are stopped in the low state. All clocks maintain a valid high period on transitions from running to stopped and on transitions from stopped to running when the chip was not powered down. On power up, the VCOs will stabilize to the correct pulse widths within 0.2 mS. The CPU and PCI clocks transition between running and stopped by waiting for one positive edge on PCI_F followed by a negative edge on the clock of interest, after which high levels of the output are either enabled or disabled.

PWR_DWN#	CPU_STOP#	PCI_STOP#	CPUCLK	PCICLK	OTHER CLKs	XTAL & VCOs
1	0	0	LOW	LOW	RUNNING	RUNNING
1	0	1	LOW	RUNNING	RUNNING	RUNNING
1	1	0	RUNNING	LOW	RUNNING	RUNNING
1	1	1	RUNNING	RUNNING	RUNNING	RUNNING
0	x (don't care)	x (don'tcare)	LOW	LOW	LOW	OFF

Power Management Timing



Power Management Timing

		Latency
Signal	Signal State	No. of rising edges of free running PCICLK (PCIF)
CPU_ST0P#	0 (disabled)	1
	1 (enabled)	1
PCI_ST0P#	0 (disabled)	1
	1 (enabled)	1

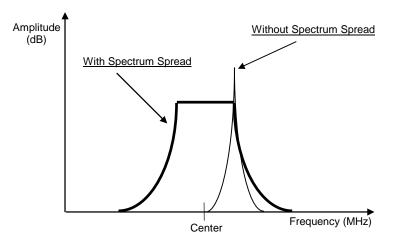
NOTES:

1. Clock on/off latency is defined in the number of rising edges of free running PCI CLOCK between the clock disable goes low/high to the first valid clock comes out of the device.



Spectrum Spread Clocking

Down Spread



Spectrum Analysis

Maximum Ratings

Voltage Relative to VSS:	-0.3V
Voltage Relative to VDD:	0.3V
Storage Temperature:	-65°C to + 150°C
Operating Temperature:	0°C to +70°C
Maximum Power Supply:	7V

This device contains circuitry to protect the inputs against damage due to high static voltages or electric field; however, precautions should be taken to avoid application of any voltage higher than the maximum rated voltages to this circuit. For proper operation, Vin and Vout should be constrained to the range: VSS<(Vin or Vout)<VDD

Unused inputs must always be tied to an appropriate logic voltage level (either VSS or VDD).



Electrical Characteristics

Characteristic	Symbol	Min	Тур	Мах	Units	Conditions
Input Low Voltage	VIL	-	-	0.8	Vdc	-
Input High Voltage	VIH	2.0	-	-	Vdc	-
Input Low Current	IIL			-66	μA	
Input High Current	IIH			5	μA	
Output Low Voltage IOL = 4mA	VOL	-	-	0.4	Vdc	All Outputs (see buffer spec)
Output High Voltage IOH = 4mA	VOH	2.4	-	-	Vdc	All Outputs Using 3.3V Power (see buffer spec)
Tri-State leakage Current	loz	-	-	10	μA	
Dynamic Supply Current	ldd	-	-	140	mA	CPU = 66.6 MHz, PCI = 33.3 MHz
Static Supply Current	lsdd	-	-	70	μA	pwr_dwn# (PIN17) = 0
Short Circuit Current	ISC	25	-	-	mA	1 output at a time - 30 seconds
VDD =	= VDDP=VI	DDR =3.	. 3V ±5%	, VDDC =	2.5V ±5%,,	TA = 0°C to +70°C

Switching Characteristics

Characteristic	Symbol	Min	Тур	Мах	Units	Conditions			
Output Duty Cycle	-	45	50	55	%	Measured at 1.5V			
CPU to PCI Offset	tOFF	1	3	4	ns	15 pf Load Measured at 1.5V			
Buffer out Skew All CPU and PCI Buffer Outputs	tSKEW	-	-	250	ps	15 pf Load Measured at 1.5V			
∆Period Adjacent Cycles	ΔΡ	-	-	<u>+</u> 250	ps	-			
Jitter Spectrum 20 dB Bandwidth from Center	BWJ			500	KHz				
VDD = VDDP =VDDR =3.3V ±5%, VDDC = 2.5V ±5%,, TA = 0°C to +70°C									



Buffer Characteristics

Buffer Characteristics for CPUCLK(0:1)

Characteristic	Symbol	Min	Тур	Max	Units	Conditions
Pull-Up Current Min	IOH _{min}	-40	-	-	mA	Vout = VDD - 0.5V
Pull-Up Current Max	IOH _{max}	-74	-	-	mA	Vout = 1.25V
Pull-Down Current Min	IOL _{min}	55	-	-	mA	Vout = 0.4V
Pull-Down Current Max	IOL _{max}	75	-	-	mA	Vout = 0.6V
Dynamic Output Impedance	Zo	10	-	15	Ohms	66 and 100 MHz
Rise Time Between 0.4 V and 2.0 V	TR	0.4	-	1.6	nS	20 pF Load
Fall Time Between 0.4 V and 2.0 V	TF	0.5	-	1.6	nS	20 pF Load
VDD = VDDP=	VDDR =3.3V ±	5 %, VD	DC = 2.5	V ±5%,, T	A = 0°C to +	-70ºC

Buffer Characteristics for REF, 48M

Characteristic	Symbol	Min	Тур	Max	Units	Conditions						
Pull-Up Current Min	IOH _{min}	-13	-	-	mA	Vout = VDD - 0.5V						
Pull-Up Current Max	IOH _{max}	-30	-	-	mA	Vout = 1.5V						
Pull-Down Current Min	IOL _{min}	13	-	-	mA	Vout = 0.4V						
Pull-Down Current Max	IOL _{max}	30	-	-	mA	Vout = 1.5V						
Dynamic Output Impedance	Zo	18	-	25	Ohms	66 and 100 MHz						
Rise Time Between 0.4 V and 2.4 V	TR	0.5	-	2.0	nS	20 pF Load						
Fall Time Between 0.4 V and 2.4 V	TF	0.5	-	2.0	nS	20 pF Load						
VDD = VDDP=	VDDR =3.3V ±	5%, VC	VDD = VDDP= VDDR =3.3V ±5%, VDDC = 2.5V ±5%,, TA = 0°C to +70°C									

Buffer Characteristics for PCI_F, PCI(1:5)

Characteristic	Symbol	Min	Тур	Max	Units	Conditions
Pull-Up Current Min	IOH _{min}	-18	-	-	mA	Vout = $VDD - 0.5V$
Pull-Up Current Max	IOH _{max}	-44	-	-	mA	Vout = 1.5V
Pull-Down Current Min	IOL _{min}	18	-	-	mA	Vout = 0.4V
Pull-Down Current Max	IOL _{max}	50	-	-	mA	Vout = 1.5V
Dynamic Output Impedance	Zo	14	-	20	Ohms	66 and 100 MHz
Rise Time Between 0.4 V and 2.4 V	TR	0.5	-	2.0	nS	30 pF Load
Fall Time Between 0.4 V and 2.4 V	TF	0.5	-	2.0	nS	30 pF Load
VDDP= VD	DR =3.3V ±5%,	VDDC	= 2.5V ±	5 %,, TA =	0°C to +70°	C



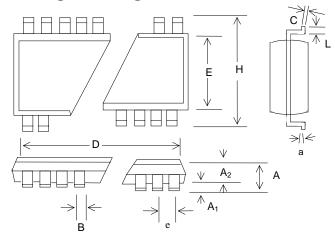
Characteristic	Symbol	Min	Тур	Max	Units	Conditions			
Frequency	Fo	12.00	14.31818	16.00	MHz				
Tolerance	тс	-	-	+/-100	PPM	Calibration Note 1			
	TS	-	-	+/- 100	PPM	Stability (Ta -10 to +60C) Note 1			
	TA	-	-	5	PPM	Aging (first year @ 25C) Note 1			
Mode	OM	-	-	-		Parallel Resonant			
Pin Capacitance	CP		5		pF	Capacitance of XIN and Xout pins			
DC Bias Voltage	V _{BIAS}	0.3Vdd	Vdd/2	0.7Vdd	V				
Startup time	Ts	-	-	30	μS				
Load Capacitance	CL	-	20	-	pF	Note 1			
Effective Series resonant resistance	R1	-	-	40	Ohms				
Power Dissipation	DL	-	-	0.10	mW	Note 1			
Shunt Capacitance	CO	-		7	pF				
X1 and X2 Load	CL		17		pF	Internal crystal loading capacitors on each pin (to ground)			
For maximum accuracy, the total circuit loading capacitance should be equal to CL. This loading capacitance is the effective capacitance across the crystal pins and includes the device pin capacitance (CP) in parallel with any circuit traces, the clock generator and any onboard discrete load capacitors. Budgeting Calculations Typical trace capacitance, (< half inch) is 4 pF, Load to the crystal is therefore 2.0 pF Clock generator internal pin capacitance of 36 pF, Load to the crystal is therefore 18.0 pF the total parasitic capacitance would therefore be = 20.0 pF(matching CL)									

Crystal and Reference Oscillator Parameters

Note 1: It is recommended but not mandatory that a crystal meets these specifications.



Package Drawing and Dimensions



28 Pin SSOP Outline Dimensions

		INCHES		MILLIMETERS			
SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX	
А	0.068	0.073	0.078	1.73	1.86	1.99	
A ₁	0.002	0.005	0.008	0.05	0.13	0.21	
A2	0.066	0.068	0.070	1.68	1.73	1.78	
В	0.010	0.012	0.015	0.25	0.30	0.38	
С	0.005	0.006	0.009	0.13	0.15	0.22	
D	0.397	0.402	0.407	10.07	10.20	10.33	
E	0.205	0.209	0.212	5.20	5.30	5.38	
е	0.	0256 BSC	;		0.65 BS	С	
Н	0.301`	0.307	0.311	7.65	7.80	7.90	
а	0°	4°	8 °	0°	4 °	8°	
L	0.022	0.030	0.037	0.55	0.75	0.95	

Ordering Information

Part Number	Package Type	Production Flow
SG556BYB	28 PIN SSOP	Commercial, 0°C to +70°C

<u>Note</u>: The ordering part number is formed by a combination of device number, device revision, package style, and screening as shown below.

Marking:	Example:	Cypress
-	-	SG556BYB
		Date Code, Lot #

SG556BYB B = Commercial, 0°C to + 70°C Package Y = SSOP <u>Revision</u> <u>Device Number</u>



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